

Report NO.: MG00001000027

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJPF130SN10
Package Type :	TO-220F

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.76%
Lead Frame	Iron	7439-89-6	0.15%	43.76%
	Phosphorus	7723-14-0	0.04%	
	Copper	7440-50-8	99.80%	
	Silver	7440-22-4	0.01%	
	Lead	7439-92-1	92.50%	
Soft Solder	Tin	7440-31-5	5.00%	0.39%
	Silver	7440-22-4	2.50%	
	Aluminium	7429-90-5	100.00%	
Mold Compound	Crystalline Silica	14808-60-7	60-82%	53.64%
	Fused Silica	60676-86-0	0-15%	
	Epoxy Resin	29690-82-2	5-15%	
	Phenol Resin	9003-35-4	5-10%	
	Me(OH)x	Trade secret	0.2-2%	
	P compounds	Trade secret	0.2-2%	
	Carbon Black	1333-86-4	0.1-0.5%	
Plating	Tin	7440-31-5	100.00%	0.08%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.